

# **LOCTITE ABLESTIK NCA 2370B**

April 2019

#### PRODUCT DESCRIPTION

LOCTITE ABLESTIK NCA 2370B provides the following product characteristics:

| Technology                    | Epoxy hybrid  |  |
|-------------------------------|---|--|
| Appearance                    | Black liquid  |  |
| Product Benefits              | <ul> <li>One component</li> <li>Non-conductive</li> <li>Low temperature cure</li> <li>Well control RBO</li> <li>Good adhesion</li> <li>High elongation strength</li> <li>Low modulus</li> </ul> |  |
| Cure                          | Heat cure   |  |
| Application                   | Component assembly, NCA (Non Conductive Adhesive)   |  |
| Typical Assembly Applications | Camera module and FPS assembly  |  |

LOCTITE ABLESTIK NCA 2370B is designed for heat sensitive applications requiring a low cure temperature. It is a one part adhesive formulated to provide good adhesion when used on a wide range of materials. This product is particularly suited where low curing temperatures are required for heat sensitive components. LOCTITE ABLESTIK NCA 2370B provides protection for solder joints against induced stress, increasing drop test performance of the device.

## TYPICAL PROPERTIES OF UNCURED MATERIAL

| Viscosity, Brookfield CP51, 25 °C, mPa·s (cP): |        |
|--|--------|
| Speed 5 rpm                                    | 18,000 |
| Thixotropic Index (0.5/5 rpm)                  | 4.4    |
| Work Life @ 25°C, days                         | 3      |
| Shelf Life @ -20°C, days                       | 180    |
| Flash Point - See SDS                          |        |

#### **TYPICAL CURING PERFORMANCE**

#### **Recommended Heat Cure Schedule**

30 minutes @ 80°C in Conventional oven

### Weight Loss

Weight Loss on Cure, @ 80°C after 30 minutes, % 0.1

#### Shrinkage on Cure

Cure Shrinkage, % 2.5

With all curing systems, the time required for cure depends on the rate of heating. Cure rate depends on the mass of material to be heated and intimate contact with the heat source. Use suggested cure conditions as general guidelines. Other cure conditions may yield satisfactory results.

The above cure profile is a guideline recommendation. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

#### TYPICAL PROPERTIES OF CURED MATERIAL

Sample cured 30 minutes @ 80°C.

#### **Physical Properties**

| Hardness, Shore D                            | 65    |
|--|-------|
| Glass Transition Temperature (Tg) by TMA, °C | 31    |
| Coefficient of Thermal Expansion, ppm/°C:    |       |
| Below Tg                                     | 49    |
| Above Tg                                     | 175   |
| Tensile Modulus @ 25 °C, DMTA, MPa           | 2,000 |
| Elongation @ break by Texture, %             | 70    |

#### TYPICAL PERFORMANCE OF CURED MATERIAL

Sample cured 30 minutes @ 80°C.

#### **Shear Strength**

Die Shear Strength, 2 x 2 mm Si die, kg/die:

| Post Cure:                    |      |
|-------------------------------|------|
| on LCP                        | 9.3  |
| on EMC                        | 12.7 |
| on PCB                        | 12.6 |
| on PA 9T                      | 12.8 |
| After 120 hours @ 85°C/85% RI | H:   |
| on LCP                        | 7.8  |
| on EMC                        | 10.2 |
| on PCB                        | 12.9 |
| on PA 9T                      | 11.6 |
|                               |      |

#### **GENERAL INFORMATION**

For safe handling information on this product, consult the Safety Data Sheet, (SDS).

#### Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.



#### **DIRECTIONS FOR USE**

- Complete cleaning of the substrates should be performed to remove contamination such as oxide layers, dust, moisture, salt and oils which can cause poor adhesion or corrosion in a bonded part.
- Some filler settling is common during shipping and storage. For this reason, it is recommended that the contents of the shipping container be thoroughly mixed prior to use.
- For best performance bond surfaces should be clean and free from grease.
- Apply adhesive to all surfaces to be bonded and join together.
- Usable shelf life may vary depending on method of application and storage conditions.

#### STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -20°C. Storage below -25°C or greater than -15°C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

#### Conversions

(°C x 1.8) + 32 = °F kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb/F N/mm x 5.71 = lb/in psi x 145 = N/mm<sup>2</sup> MPa = N/mm<sup>2</sup> N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

#### Disclaimer

#### Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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